

ABSTRACT

GRINDING WHEEL, GRINDING APPARATUS, AND METHOD OF GRINDING WAFER

Disclosed herein is a grinding wheel including an annular wheel base and a plurality of grinding stones fixed to an outer circumferential portion of the lower end of the annular wheel base. Each of the grinding stones is made of a mixture of abrasive grains and photocatalytic particles which are held together by a binder. The abrasive grains are diamond abrasive grains, and the photocatalytic particles are titanium oxide (TiO₂) particles.

(Figure 1)